

### **TECHNOLOGIES, INC.**

## 12 Watt ♦ 4 GHz ♦ GaN on SiC ♦ Packaged Transistor

- ♦ GaN HEMT Technology
- ♦ All Gold Metal System
- ◆ Broadband Unmatched Design
- ◆ Frequency of Operation: DC to 4GHz
- ♦ 28V Operation
- ♦ S-Parameter CAD Files Available Upon Request



## **Absolute Maximum Ratings**

Parameter	Symbol	Rating	Units	Conditions
Drain Voltage	$V_D$	40	V	25°C
Gate Voltage	$V_{G}$	-50 to 0	V	25°C
Drain-Gate Voltage	$V_{DG}$	80	V	25°C
Drain Current	I <sub>D</sub>	2.5	Α	25°C
Gate Current	I <sub>G</sub>	14	mA	25°C
Input CW Power	P <sub>IN</sub>	34	dBm	25°C
Storage Temperature	T <sub>STG</sub>	-55 to +150	°C	
Channel Temperature	T <sub>CH</sub>	200	°C	

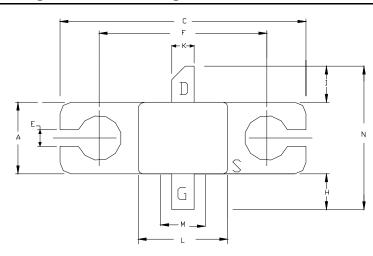
### **Parameters**

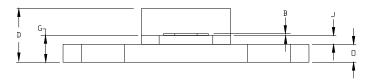
Parameter	Symbol	Min	Тур	Max	Units	Conditions
Gate Threshold Voltage	$V_{GS(TH)}$	-	-3.6		V	V <sub>DS</sub> = 28 V, I <sub>D</sub> = 250 mA
Capacitance Gate-Source	$C_{GS}$		3.6		pF	$V_{DS}$ = 28 V, $I_{D}$ = 250 mA
Capacitance Gate-Drain	$C_{GD}$		0.12		pF	V <sub>DS</sub> = 28 V, I <sub>D</sub> = 250 mA
Capacitance Drain-Source	$C_{ extsf{DS}}$		0.6		pF	V <sub>DS</sub> = 28 V, I <sub>D</sub> = 250 mA
Gain	G		18		dB	Note 1
Power Output Saturated	P <sub>SAT</sub>		41		dBm	Note 1
Power Added Efficiency	PAE	1	58		%	Note 1
Leak Rate	LR			1x10 <sup>-3</sup>		Rate per MIL-STD-750D, atm-cm <sup>3</sup> /sec
Thermal Resistance	JC			8.0	°C/W	Note 1, P <sub>OUT</sub> = 41dBm
Note 1: V <sub>DD</sub> =28V, I <sub>DQ</sub> = 250mA, T <sub>F</sub> =25	°C, F=3.0GHz.			-	-	



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# **Package Outline Drawing**





	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
А	0.155	0.165	3.94	4.19	
В	0.003	0.006	0.07	0.15	
С	0.545	0.555	13.84	14.09	
D	0.112	0.146	2.84	3.70	
Ε	0.027	0.037	0,68	0.94	
F	0.370	0.380	9.40	9.65	
G	0.057	0.067	1.45	1.70	
Н	0.060	0.100	1.52	2.54	
Ι	0.060	0.100	1.52	2.54	
J	0.015	0.025	0.38	0.63	
K	0.045	0.055	1.14	1.40	
L	0.195	0.205	4.95	5.21	
М	0.165	0.175	4.19	4.44	
N	0.315	0.325	8.00	8.25	
	0.035	0.045	0.89	1.14	

PIN S	SCHEDULE
D	DRAIN
S	SOURCE
G	GATE



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### **Definitions**

Data Sheet Status		
Proposed Specification	This data sheet contains proposed specifications.	
Preliminary Specification	This data sheet contains specifications based on preliminary measurements and data.	
Product Specification	This data sheet contains final product specifications.	

#### **Maximum Ratings**

Stress above one or more of the maximum ratings may cause permanent damage to the device. These are maximum ratings only operation of the device at these or at any other conditions above those given in the characteristics sections of the specification is not implied. Exposure to maximum values for extended periods of time may affect device reliability.

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